

Product Change Notification - KSRA-20BGKY389

Date:

14 Feb 2020

Product Category:

8-bit Microcontrollers

Affected CPNs:



Notification subject:

CCB 4023.001 and 4023.002 Final Notice: Qualification of MTAI as a new assembly site for selected Atmel products available in 32L (7x7x1.0mm) and 48L TQFP (7x7x1.0mm) package using gold (Au) wire.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MTAI as a new assembly site for selected Atmel products available in 32L (7x7x1.0mm) and 48L TQFP (7x7x1.0mm) package using gold (Au) wire.

Pre Change:

Assembled at ASCL assembly site using palladium coated copper with gold flash (CuPdAu) bond wire, G700 and CEL-9240 molding compound, EN4900G die attach, and C194-ESH lead frame material with MSL Level 3 classification

Post Change:

Assembled at MTAI assembly site using gold (Au) bond wire, G700 molding compound, 3280 die attach, and C7025 lead frame material with MSL Level 1 classification

Pre and Post Change Summary:

	Pre C	hange	Post Change				
Assembly Site	ASE Group Ch	una Li / ASCI	Microchip Technology				
Assembly Site	ASE Gloup Ci	lulig-Li / ASCL	Thailand (HQ) / MTAI				
Wire material	CuP	'dAu	Au				
Die attach material	EN49	900G	3280				
Molding compound material	G700	CEL-9240	G700				
Lead frame material	C194	-ESH	C7025				
MSL	MS	L 3	MSL 1				

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity by qualifying MTAI as a new assembly site

Change Implementation Status:

In Progress

Estimated First Ship Date:

March 14, 2020(date code: 2011)



NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	December 2019		₩ 	February 2020				March 2020							
Workweek	49	50	51	52		05	06	07	08	09	10	11	12	13	14
Initial PCN Issue Date				Χ											
Qual Report Availability								Х							
Final PCN Issue Date								Χ							
Estimated Implementation Date												X			

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

December 23, 2019: Issued initial notification.

February 14, 2020: Issued final notification. Attached the Qualification Report. Updated the pre and post change to add CEL-9240 molding compound material. Provided estimated first ship date to be on March 14, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN KSRA-20BGKY389 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.

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If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ATMEGA168PB-AU

ATMEGA168PB-AN

ATMEGA168PB-ANR

ATMEGA168PB-AUR

ATMEGA88PB-AU

ATMEGA48PB-AU

ATMEGA88PB-AN

ATMEGA48PB-AN

ATMEGA88PB-ANR

ATMEGA48PB-ANR

ATMEGA88PB-AUR

ATMEGA48PB-AUR

ATMEGA808-AF

ATMEGA1608-AF

ATMEGA1608-AU

ATMEGA808-AU

ATMEGA1608-AUR

ATMEGA808-AUR

ATMEGA1608-AFR

ATMEGA808-AFR

ATMEGA328PB-AU

ATMEGA328PB-AN

ATMEGA328PB-ANR

ATMEGA328PB-AUR

ATMEGA4808-AF

ATMEGA3208-AF

ATMEGA4808-AU

ATMEGA3208-AU

ATMEGA4808-AUR

ATMEGA3208-AUR

ATMEGA4808-AFR

ATMEGA3208-AFR

ATMEGA809-AF

ATMEGA1609-AF

ATMEGA1609-AU

ATMEGA809-AU

ATMEGA1609-AUR

ATMEGA809-AUR

ATMEGA1609-AFR

ATMEGA809-AFR

ATMEGA4809-AF

ATMEGA3209-AF

ATMEGA4809-AU

ATMEGA3209-AU

ATMEGA4809-AUR

ATMEGA3209-AUR

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ATMEGA4809-AFR
ATMEGA3209-AFR
Date: Thursday, February 13, 2020